Attorney's Docket	No.:
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DECLARATION, POWER OF ATTORNEY AND PETITION

I (We), the undersigned inventor(s), hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I (We) believe that I am (we are) the original, first, and joint (sole) inventor(s) of the subject matter which is claimed and for which a patent is sought on the invention entitled

SOLUTION FOR SUBSTRATE SPOTTING AND SPOTTING METHOD

e spe	cification of which	
	is attached hereto.	
	☐ was filed on	a s
	Application Serial No.	
	and amended on	·
	☐ was filed as PCT international application	
	Number	
	on	,
	and was amended under PCT Article 19	
	o n	(if applicable).

I (We) hereby state that I (We) have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above; that I (We) do not know and do not believe that this invention was ever known or used before my invention or discovery thereof, or patented or described in any printed publication in any country before my invention or discovery thereof, or more than one year prior to this application, or in public use or on sale in the United States for more than one year prior to this application; that this invention or discovery has not been patented or made the subject of an inventor's certificate in any country foreign to the United States on an application filed by me or my legal representatives or assigns more than twelve months before this application.

I (We) acknowledge the duty to disclose information known to be material to the patentability of this application as defined in Section 1.56 of Title 37 Code of Federal Regulations.

I (We) hereby claim foreign priority benefits under Section 119(a)-(d) of Title 35 United States Code, of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

			Priori	t y	
Application No.	Country	Filing date	claime	ed	
2002-187711	Japan	June 27, 2002	■ Yes	□ No	
			☐ Yes	□ No	
			☐ Yes	□ No	
			☐ Yes	□ No	
of any United Stat	tes application((s) listed below.			
(Application Num	nber)	(Filing Date)		
(Application Num	nber)	(Filing Date	•)		

I (We) hereby claim the benefit under Section 120 of Title 35 United States Code, of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Section 112 of Title 35 United States Code, I (We) acknowledge the duty to disclose material information as defined in Section 1.56(a) of Title 37 Code of Federal Regulations, which occurred between the filing date of the prior application and national or PCT international filing date of this application:

		Status (pending,
		patented,
Application Serial No.	Filing Date	abandoned)
		
And I (We) hereby appoint:	Stanley P. Fisher, Registrati	on No. 24,344 and Juan Carlos
Marquez, Registration No. 34,072.	,	
I(We) hereby request that all corre	espondence regarding this ap	oplication be sent to the firm of Reed
Smith Hazel & Thomas LLP whose	Post office address is: 3110 I	Fairview Park Drive, Suite 1400, Falls
Church, Virginia 22042-4503 U.S.A	. .	
I (We) declare further that	all statements made he	erein of my (our) knowledge
are true and that all states	ments were made with	the knowledge that willful
false statements and the lik	e so made are punishab	le by fine or imprisonment,
or both, under Section 100	1 of Title 18 of the Uni	ted States Code and that such
willful false statements ma	y jeopardize the validi	ity of the application or any
patent issued thereon.		
Yasuo KOMATSU	Residenc	e: Kanagawa, Japan
NAME OF FIRST INVENTOR		
$\Omega \Lambda$	<i></i>	
Jasuo Con	Citizen of	: Japan
Signature of Inventor	Post Offic	e Address:
	c/o DNA	Chip Research Inc.,
Jüne 16, 2003	1-43, Sue	hiro-cho 1-chome,

Date

Tsurumi-ku, Yokohama-shi,

Kanagawa 230-0045 Japan

Kenichi MATSUBARA	Residence: <u>Kanagawa, Japan</u>
NAME OF SECOND INVENTOR	
Keindin Meterbara	Citizen of: <u>Japan</u>
Signature of Inventor	Post Office Address:
	c/o DNA Chip Research Inc.,
June 16, 2003	1-43, Suehiro-cho 1-chome,
Date	Tsurumi-ku, Yokohama-shi,
	Kanagawa 230-0045 Japan
•	
Eiko OHTSUKA	Residence: <u>Kanagawa, Japan</u>
NAME OF THIRD INVENTOR	
Gino Datoulan	Citizen of: Japan
Signature of Inventor	Post Office Address:
	c/o DNA Chip Research Inc.,
June 16, 2003	1-43, Suehiro-cho 1-chome,
Date	Tsurumi-ku, Yokohama-shi,
	Kanagawa 230-0045 Japan
Ken NONAKA	Pasidanas Vanagawa Janan
NAME OF FOURTH INVENTOR	Residence: <u>Kanagawa, Japan</u>
KEN NONAKA	Citizen of: Japan
Signature of Inventor	Post Office Address:
	c/o DNA Chip Research Inc.,
June 16, 2003	1-43, Suehiro-cho 1-chome,
Date	Tsurumi-ku, Yokohama-shi,
	Kanagawa 230-0045 Japan

Noriko YURINO	Residence: <u>Tokyo, Japan</u>
NAME OF FIFTH INVENTOR	
NORIKO YURIND	Citizen of: <u>Japan</u>
Signature of Inventor	Post Office Address:
	c/o Hitachi Software Engineering Co., Ltd
June 16, 2003	4-12-7, Higashishinagawa,
Date	Shinagawa-ku, Tokyo 140-0002 Japan
	Residence:
NAME OF SIXTH INVENTOR	
	Citizen of:
Signature of Inventor	Post Office Address:
Date	
	Residence:
NAME OF SEVENTH INVENTOR	
	Citizen of:
Signature of Inventor	Post Office Address:
Date	